

Remarks

Reconsideration of this application as amended is respectfully requested.

Claims 1-20 stand rejected under 35 U.S.C. §103(a) as being unpatentable over U.S. Patent No. 4,008,564 of *Luce et al.* ("*Luce*").

The Examiner has objected to the drawings as not including references 70, 72, and 100. In response, applicant submits herewith a corrected Figure 7 that includes references 70, 72, and 100.

Claims 2, 5, 7-11, 16, and 19 have been cancelled. New claims 21-26 have been added.

The Examiner has rejected claims 1-20 under 35 U.S.C. §103(a) as being obvious in view of *Luce*. Applicant respectfully submits, however, that amended claim 1 is not obvious in view of *Luce* because *Luce* does not disclose or suggest a structure disposed on an enclosure of an electronic component that is provided to reduce a thermal drift in the electronic component by increasing a thermal mass of the electronic component as claimed in amended claim 1. Instead, *Luce* discloses a potting material 46 disposed on a can 40 that encloses a device 32 which is provided to seal the device 32 from the atmosphere. (*Luce*, col. 4, lines 31-56).

Luce does not teach or suggest that the potting material 46 or the can 40 increase the thermal mass of the device 32. Instead, *Luce* teaches that the can 40 and the potting material 46 seal the device 32 from the atmosphere (*Luce*, col. 4, lines 31-32) and that the potting material 46 facilitates the attachment of a wrist band (*Luce*, col. 4, lines 57-60).

It is further submitted that the can 40 and the potting material 46 of *Luce* do not increase the thermal mass of the device 32 because the can 40 and the potting material 46 are thermally isolated from the device 32.

For example, the can 40 is isolated from a substrate 10 that holds the device 32 by an insulator 42 (*Luce*, Fig. 2 and col. 4, lines 36-41) and is separated from a support plate 30 of the device 32 by a spring mechanism 44 which is used to facilitate assembly (*Luce*, Fig. 2 and col. 4, lines 45-48).

It is therefore respectfully submitted that the circuit of amended claim 1 that includes a structure disposed on an enclosure of an electronic component and that is provided to reduce a thermal drift in the electronic component by increasing a thermal mass of the electronic component is not obvious in view of the structures of *Luce* that seal a device from the atmosphere and that are thermally isolated from the device.

Given that claims 3-4, 6, and 12-14 depend from amended claim 1, it is submitted that claims 3-4, 6, and 12-14 are not obvious in view of *Luce*.

It is also submitted that amended claim 15 is not obvious in view of *Luce*. Amended claim 15 recites a crystal component and a structure for reducing thermal drift in the crystal component by increasing a thermal mass of the crystal component. *Luce* does not disclose or suggest a structure for reducing thermal drift in the crystal component by increasing a thermal mass of the crystal component as claimed in amended claim 15. Instead, *Luce* discloses a can 40 that encloses a device 32 and that is thermally isolated from the device 32. (*Luce*, Fig. 2 and col. 4, lines 36-41).

Given that claims 17-18 and 20 depend from amended claim 15, it is submitted that claims 17-18 and 20 are not obvious in view of *Luce*.

Applicant further submits that new claim 21 is not obvious in view of *Luce*. New claim 21 recites an electronic component and a structure for thermally isolating the electronic component from a set of other

components of a circuit. *Luce* does not disclose or suggest a structure for thermally isolating an electronic component from a set of other components of a circuit as claimed in new claim 21. Instead, *Luce* discloses a substrate 10 holds both the device 32 and a set of other circuit elements 98. (*Luce*, Fig. 2 and col. 4, lines 10-13).

The Examiner has stated that

Luce et al. further disclose wherein the system comprises a circuit board that holds the electronic component which is separated from a circuit board that holds a set of other components of the circuit [10 and 30; figure 2.)

(Page 3, Office Action, 2-17-04) (emphasis added).

Applicant respectfully submits that elements 10 and 30 of *Luce* are not separate circuit boards that separate an electronic component from other components of a circuit as claimed in new claim 21. Instead, Fig. 2 of *Luce* clearly shows that the support plate 30 is encased in the can 40 of the device 32 while the substrate 10 holds both the device 32 and the other circuit elements 98 without thermal isolation between as claimed in new claim 21.

Given that new claims 22-26 depend from new claim 21, it is submitted that new claims 22-26 are not obvious in view of *Luce*.

It is respectfully submitted that in view of the amendments and arguments set forth above, the applicable objections and rejections have been overcome.

The Commissioner is authorized to charge any underpayment or credit any overpayment to Deposit Account No. 50-1078 for any matter in connection with this response, including any fee for extension of time, which may be required.

Respectfully submitted,

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